

Silicon Carbide (SiC) MOSFET - 20 mohm, 900 V, M2, TO-247-4L

NVH4L020N090SC1

Features

- Typ. $R_{DS(on)} = 20 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$ Typ. $R_{DS(on)} = 16 \text{ m}\Omega$ @ $V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge (typ. $Q_{G(tot)} = 196 \text{ nC}$)
- Low Effective Output Capacitance (typ. Coss = 296 pF)
- 100% UIL Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

Typical Applications

- Automotive Traction Inverters
- Automotive On Board Charger
- Automotive DC-DC Converter for EV/HEV

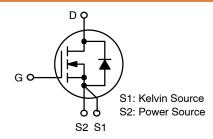
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	900	٧
Gate-to-Source Voltag	де		V _{GS}	+22/-8	V
	Recommended Operation T _C < 175°C Values of Gate–Source Voltage				V
Continuous Drain Current R _{0JC}	,		I _{DC}	116	Α
·			P _{DC}	484	W
Continuous Drain Current R _{0JC}	Steady State	T _C = 100°C	I _{DC}	82	Α
Power Dissipation $R_{\theta JC}$			P _{DC}	242	W
Pulsed Drain Current (Note 2)	T _A = 25°C	I _{DM}	504	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	106	Α
Single Pulse Drain-to-Source Avalanche Energy (I _L = 23 A _{pk} , L = 1 mH) (Note 3)			E _{AS}	264	mJ

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. E_{AS} of 264 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 23 A, V_{DD} = 100 V, V_{GS} = 15 V.

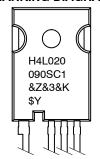
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
900 V	28 mΩ @ 15 V	118 A



N-CHANNEL MOSFET



MARKING DIAGRAM



H4L020090SC1 = Specific Device Code &Z = Assembly Plant Code &3 = Date Code (Year & Week) &K = Lot \$Y = onsemi Logo

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

Table 1. THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-to-Case (Note 1)	$R_{ heta JC}$	0.31	°C/W
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{ heta JA}$	40	°C/W

Table 2. ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Conditio	n Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•			
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	900			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, refer to 25°C		500		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 900 V			100	μΑ
Oda ta Orași la la ca Orași		$T_{J} = 1$			250	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +22/-8 \text{ V}, V_{DS} = 0$) V		±1	μΑ
ON CHARACTERISTICS	.,		1	T	l	.,
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 20$ mA	1.8	2.7	4.3	V
Recommended Gate Voltage	V_{GOP}		-5		+15	V
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 15 \text{ V}, I_D = 60 \text{ A}, T$		20	28	mΩ
		$V_{GS} = 18 \text{ V}, I_D = 60 \text{ A}, T$		16		
		$V_{GS} = 15 \text{ V}, I_D = 60 \text{ A}, T$	J = 175°C	27		
Forward Transconductance	9FS	$V_{DS} = 20 \text{ V}, I_D = 60 \text{ A}$		49		S
CHARGES, CAPACITANCES & GATE RES	ISTANCE					
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1 \text{ MHz,}$ $V_{DS} = 450 \text{ V}$		4415		pF
Output Capacitance	C _{OSS}	V _{DS} = 450 V		296		
Reverse Transfer Capacitance	C _{RSS}			24		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/15 \text{ V}, V_{DS} = 72$	20 V,	196		nC
Threshold Gate Charge	Q _{G(TH)}	I _D = 60 A		42		1
Gate-to-Source Charge	Q_{GS}			78		
Gate-to-Drain Charge	Q_{GD}			55		
Gate-Resistance	R_{G}	f = 1 MHz		1.6		Ω
SWITCHING CHARACTERISTICS			,			
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -5/15 \text{ V}, V_{DS} = 72$	20 V,	29		ns
Rise Time	t _r	I_D = 60 A, R_G = 2.5 Ω , Inductive Load		28		
Turn-Off Delay Time	t _{d(OFF)}			54		-
Fall Time	t _f			14		
Turn-On Switching Loss	E _{ON}			611		μJ
Turn-Off Switching Loss	E _{OFF}			293		
Total Switching Loss	E _{TOT}			904		
DRAIN-SOURCE DIODE CHARACTERIST	1		l	<u>.</u>	•	
Continuous Drain-Source Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}\text{C}$			106	А
Pulsed Drain–Source Diode Forward Current (Note 2)	I _{SDM}	V _{GS} = -5 V, T _J = 25°C			504	А
Forward Diode Voltage	V_{SD}	V _{GS} = -5 V, I _{SD} = 30 A,	T _{.l} = 25°C	3.8		V

Table 2. ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise stated) (continued)

Table 2. ELECTRICAL CHARACTERIOTICS (1j = 25 O dilless office wise stated) (Continued)									
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit			
DRAIN-SOURCE DIODE CHARACTERISTICS									
Reverse Recovery Time	t _{RR}	V _{GS} = -5/15 V, I _{SD} = 60 A, dI _S /dt = 1000 A/μs, V _{DS} = 720 V		30		ns			
Reverse Recovery Charge	Q_{RR}	di _S /at = 1000 A/μs, V _{DS} = 720 V		244		nC			
Reverse Recovery Energy	E _{REC}			11		μJ			
Peak Reverse Recovery Current	I _{RRM}			16		Α			
Charge Time	Ta			17		ns			
Discharge Time	Tb			13		ns			

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

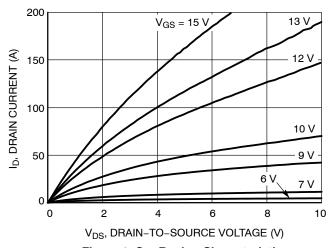


Figure 1. On-Region Characteristics

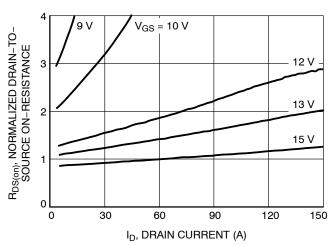


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

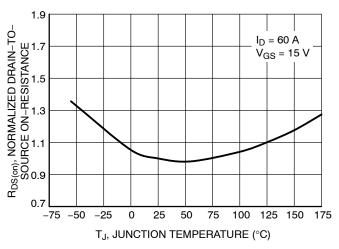


Figure 3. On–Resistance Variation with Temperature

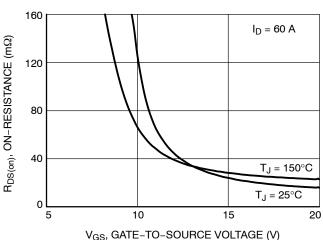


Figure 4. On-Resistance vs. Gate-to-Source Voltage

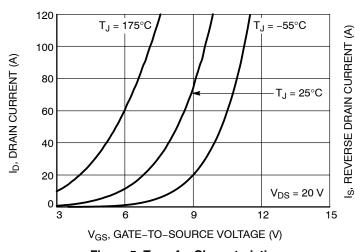


Figure 5. Transfer Characteristics

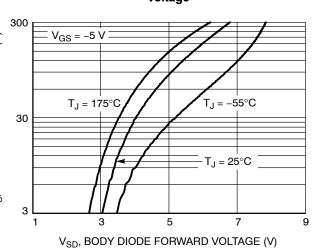
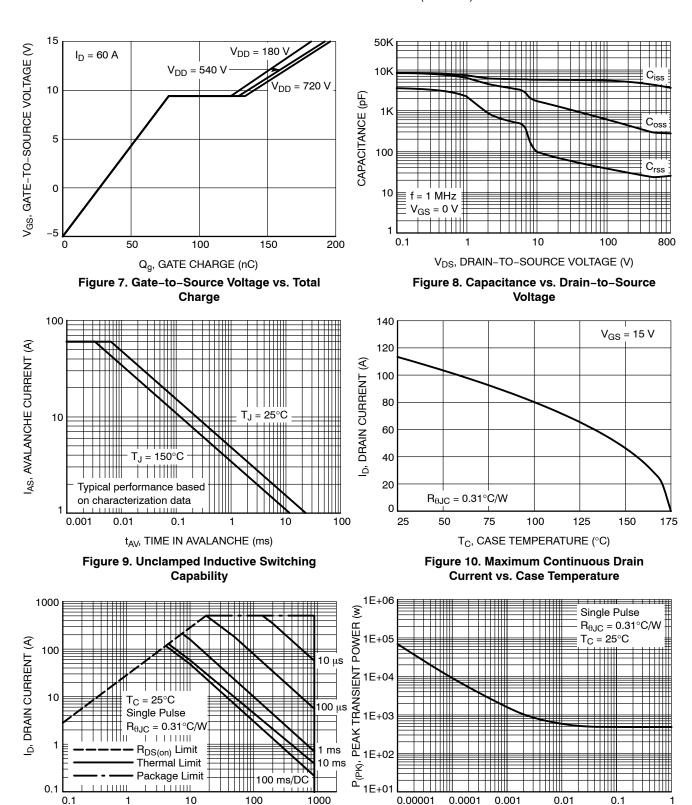


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS (continued)



V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V) Figure 11. Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation

t, PULSE WIDTH (sec)

TYPICAL CHARACTERISTICS (continued)

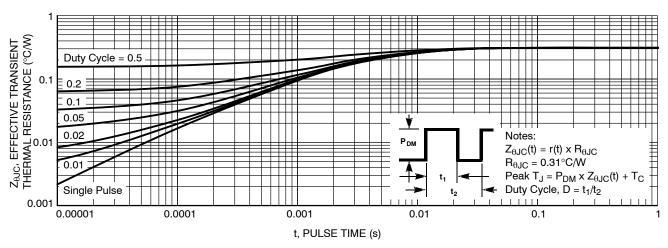


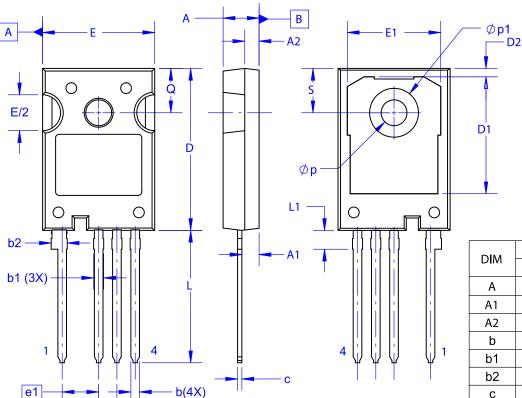
Figure 13. Junction-to-Ambient Transient Thermal Response Curve

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Size	Quantity
NVH4L020N090SC1	H4L020090SC1	TO247-4L	Tube	N/A	N/A	30 Units

TO-247-4LD CASE 340CJ **ISSUE A**

DATE 16 SEP 2019



NOTES:

e 2X-0.254 M

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 C. ALL DIMENSIONS ARE IN MILLIMETERS.
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Α	4.80	5.00	5.20	
A1	2.10	2.40	2.70	
A2	1.80	2.00	2.20	
b	1.07	1.20	1.33	
b1	1.20	1.40	1.60	
b2	2.02	2.22	2.42	
С	0.50	0.60	0.70	
D	22.34	22.54	22.74	
D1	16.00	16.25	16.50	
D2	0.97	1.37		
е	2.54 BSC			
e1	5	5.08 BSC)	
E	15.40	15.60	15.80	
E1	12.80	13.00	13.20	
E/2	4.80	5.00	5.20	
L	18.22	18.42	18.62	
L1	2.42 2.62		2.82	
р	3.40 3.60		3.80	
p1	6.60	6.80	7.00	
Q	5.97	6.17	6.37	
S	5.97	6.17	6.37	

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